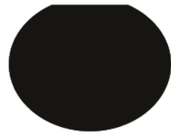


inseto

ADVANCED TECHNOLOGY FOR RESEARCH AND INDUSTRY

Inseto is a leading technical distributor of equipment and related materials to the semiconductor, microelectronic & advanced technology sectors, as well as adhesives for electronics, automotive & industrial manufacturing.

ADHESIVES

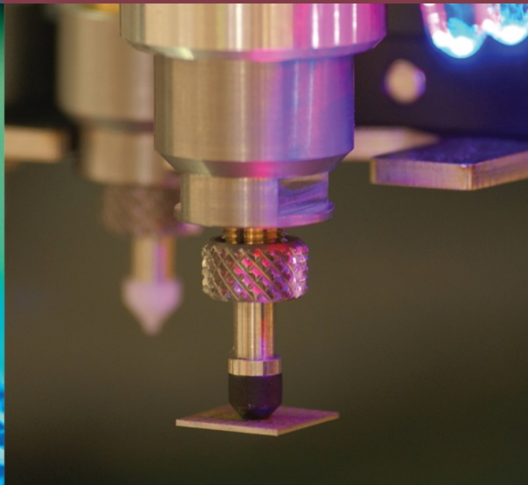
A comprehensive range of technical adhesives and sealants for the automotive, electronic and general manufacturing industries

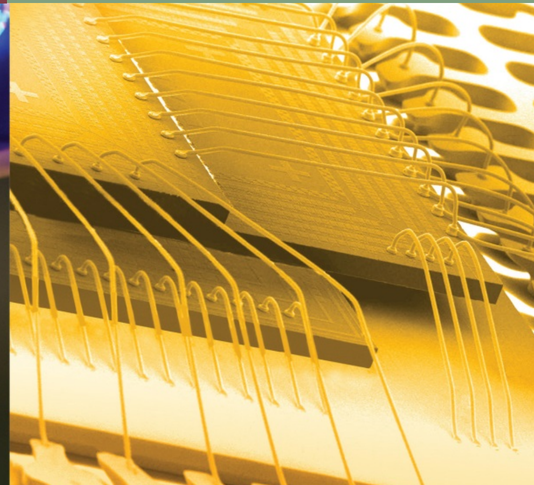
EQUIPMENT

Provides fabrication, assembly and test equipment for research and production of semiconductor devices and related technologies

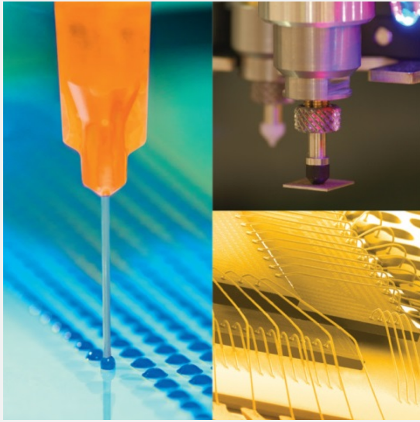
CONSUMABLES

For assembly materials and machine consumable products used in electronic, semiconductor, photonic, RF and hybrid assembly





PRODUCT PRESENTATION



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ABOUT INSETO:

An ISO 9001:2015 Accredited Company established since 1987, Inseto provides manufacturing equipment plus related materials and consumable products for the research & production of Semiconductor, Microelectronic and related advanced electronic devices etc., as well as products for high technology & industrial manufacturing.

Our range of advanced equipment and materials is available from specialist technology divisions, which offer carefully selected, technically innovative, high performance products. Further details of our Company's product range can also be found on our website: www.inseto.co.uk

Customer support activities are at the centre of Inseto's "Total Customer Service" philosophy, where we aim to understand, communicate and fulfil the needs of our customers, better than any of our competitors.

We are committed to meeting these requirements through the application of high standards of quality and customer care, both before and after sales, by continually investing in training & adopting a policy of continuous improvement in our Company and its people.

TECHNICAL SUPPORT SERVICES:

Inseto's engineering team has developed high levels of knowledge and experience in the implementation of quality support services, including Process Reviews & Improvements, Breakdowns, Certified Maintenance & Calibrations, Support Contracts, Equipment & Process Training Classes & Machine Repairs etc.

We understand that requirements may vary, depending on the size of your facility & "in house" capabilities and so will tailor our services accordingly, matching your requirements precisely. All of our work is carried out in accordance with the manufacturers guidelines using comprehensive service checklists, calibrated instruments, OEM warrantied parts and is certified according to our ISO accreditation & procedures.

INSETO

Annual Maintenance

OEM trained engineers providing annual maintenance including replacement of wear parts. Visits timed to suit customer production schedule. Visits can be every 6, 12 or 24 months. Pricing includes travel time to site

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INSETO

Equipment Calibration

ISO Certified equipment calibration by OEM trained engineers to factory standards. All engineers instruments fully traceable. E-Certificate provided within 48 hours of visit. Reduced rate for multiple single site calibrations.

INSETO

Annual Service Contracts

Support packages designed according to customer requirements. Covers single or multiple equipment types. Priority access to support spare parts. Reduced engineer response times. Single & multi-year contracts.

INSETO

Emergency Service Support

For customers not covered via a support contract, hourly charge for engineer's time. Travel expenses charged at cost. Support provided during office hours.

INSETO

Extended Support

Outside office hour's emergency service support when not covered by a support contract. Hourly charge for engineer's time. Travel expenses charged at cost.

INSETO

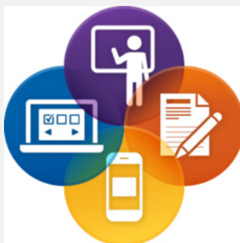
Email/Telephone Support

Available for all customers; additional charge where customer does not have any equipment originally purchased from Inseto. Provides customer access to Inseto engineers for technical assistance during office hours.

OEM

Online Support

Available on specific equipment types, provides online equipment support where the customer connects the system to the internet for diagnosis of equipment or programming error conditions.



INSETO/OEM

Training Classes

One to five day standard outline or custom training classes by OEM trained Inseto engineer, or directly by OEM. Training classes at Inseto, Customer site or OEM facility. Certificate of competence issued upon successful completion

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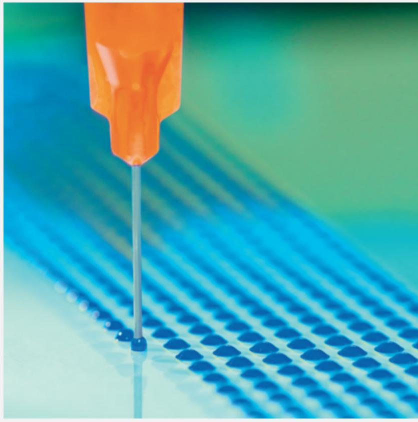
INSETO/OEM

Application Support

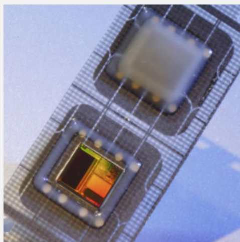
Onsite assistance by Inseto or OEM engineer to assist customer in the development of applications, including programming of machine, improvement of process settings & capability.



ADHESIVE DIVISION:

Inseto's Adhesive Division provides technically advanced adhesives for bonding, sealing & encapsulation applications to customers throughout the UK & Ireland. Exclusively representing DELO Industrial Adhesives, our specialists have the technical expertise to advise on all your project requirements.

DELO manufactures a comprehensive range of UV cured or light activated Epoxies, light cured Acrylates, light / heat cured Epoxies, light / anaerobic curing adhesives, 2 part Polyurethanes, 1 & 2 part Epoxies, Cyanoacrylates and single part Silicones. Inseto can also offer tailor-made adhesive solutions that meet your technical bonding requirements. DELO's product range comprises:



DELO-KATIOBOND

Light Activated Epoxies

UV / VIS-curing epoxy adhesives. Visible-light activated epoxies for bonding opaque components. Single-part solvent-free adhesives for bonding, sealing and potting applications. Fast-curing for short cycle times and increased throughput. High thermal and chemical resistance.

DELO-PHOTOBOND

Light Cured Acrylates

UV / VIS-curing acrylate adhesives for applications with one transparent component. Single-part solvent-free adhesives, used for rapid bonding, sealing & joining of plastics, metals and glass. Highly flexible adhesives suitable for stress-equalising applications.

DELO-DUALBOND

Light and/or Heat-Curing Epoxies & Acrylates

Combination cure of heat and / or UV light. Independent curing mechanisms. Ideal for high-accuracy applications, also for curing in shadow zones.

DELO-DUALBOND

Light and Moisture-Cured Acrylates

Dual-curing system for panel and touchscreen applications. Fast curing with UV light, subsequent moisture curing in shadow zones.

DELO-DUALBOND

Light & Anaerobic-Curing Adhesives

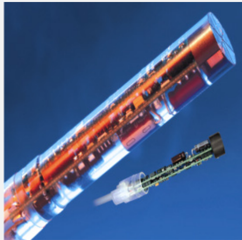
Cure anaerobically in the presence of metal ions. UV light used to cure the edge of the joint. Especially for high thermal and chemical resistance.

Image Courtesy & Copyright: ebm-Pabst GmbH & Co. KG

DELOMONOPOX

One Part Epoxies

Single-part heat-cured epoxies. Curing temperatures as low as 60°C. Very high thermal resistance up to 250°C. Used as adhesives and casting resins in electronic, electrical and mechanical engineering applications.



DELO-DUOPOX

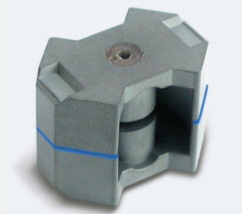
Two Part Epoxies

High strength, two-part, cold cured epoxy resin adhesives for bonding, casting and sealing of joints where curing with heat is not an option. Excellent adhesion to a wide range of materials.

DELO-PUR

Polyurethanes

Two-part cold curing adhesive for bonding, casting & sealing of joints. Available in AUTOMIX cartridges for use in high strength applications where flexibility is required or for filling of large gaps.



DELO-ML

Anaerobic Adhesives

Single-part solvent-free adhesives for bonding in the presence of metal and the absence of air. High, medium and low bond strength options. For magnet and ferrite bonding. Very high thermal and chemical resistance.

DELO-CA

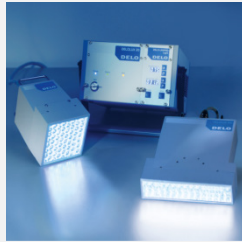
Instant Adhesives

Cyanoacrylate adhesives, moisture curing for general bonding applications. More commonly known as super glue or instant adhesives they provide an initial bond strength in seconds.

DELO-GUM

Silicone Adhesives

Moisture cured silicone adhesives. Excellent resistance to temperature, weathering, ageing & with a high elongation at tear. For fixing, sealing, potting and for where large gaps need to be filled.



DELOLUX 20
Large Area Curing Equipment

Large-area LED lamp for bigger illumination area. Available in 365nm, 400nm and 460nm options. Use in standalone mode, or in-line production. Even cure over the whole area. Long life time of 10K on-hours minimum.

DELOLUX 50
Spot Curing Equipment

Pin-point LED lamp for spot curing with very high intensity (up to 12,000 mW/cm^2). Maximum of 4 LED heads can be connected. Lens diameter from 3mm to 15mm. Available in 365nm and 400nm options. Long life time of 10K on-hours.

DELOLUX 80
High Intensity Curing Equipment

Closed circuit, liquid-cooled high intensity LED lamp. Available in 365nm, 400nm & 460nm options. Focused beam up to a distance of 25mm. Long life time of 10K on-hours minimum.

DELOLUXCONTROL
Light Intensity Measurement Equipment

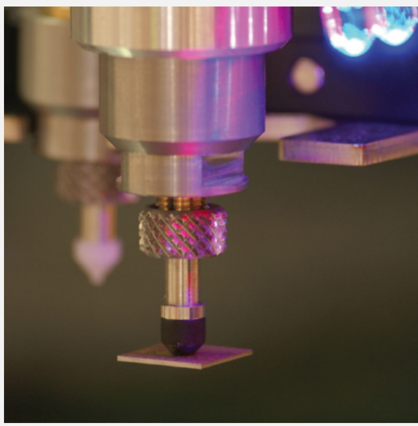
Process control light-intensity meter. Suitable for use with LED lamps and halogen-bulb lamps. Large display for easy reading. Battery operated. Very high resolution of 0.1 mW/cm^2.

DELOMAT
Dispensing Equipment

For semi to fully automatic dispensing, with up to 4 independently controlled work stations. Universal dispensing from pressure tank, cartridge & syringe. For low viscosity to pasty adhesives.

DELO-DOT-PN2
Micro Dispensing Equipment

Pneumatic dispensing valve. Combines precision, speed and slim dimensions. Cutting-edge actuator. Modular design for ease of cleaning. Easily integrated into existing production lines.



EQUIPMENT DIVISION:

Inseto's Equipment Division is a leading supplier of equipment for the manufacture of semiconductor, electronic and related devices or assemblies, including RF-Microwave, Power Electronic, Photonic, Flexible, and Bio-Medical products etc., throughout the UK, Ireland and Nordic regions.

Products include lithography equipment for alignment, exposure coating and development, wafer bonding systems, semiconductor wafer furnaces, bumping equipment, probing systems, wafer dicing and diamond scribing machines, die bonders and ultrasonic wire bonding machines, plasma cleaners and etching systems, vacuum solder reflow ovens, material testers for pull & shear testing etc.

SÜSS MicroTec
Mask Aligners & Laser Surface Imaging Equipment
High-resolution lithography systems providing exceptional reliability, maximum light uniformity, including the latest UV-LED light sources and sub-micron alignment accuracy. The product line ranges from lab aligners for piece parts up to 100mm substrates, through 150, 200 & 300mm systems, with optional imprint and bond alignment capability, to automated systems & Laser Surface Imaging equipment for mask free pattern generation.

SÜSS MicroTec
Spin Coaters, Spray Coaters, Developer & Hotplates
With a complete line of compact and user-friendly resist coating equipment from economic low-volume table-top and laboratory tools to high-end production systems up to 300 mm, SUSS MicroTec spin coaters, spray coaters, developer and hot-plates, enable the formation of resist layers ranging from below 1 µm to over 500 µm.

SÜSS MicroTec
Wafer Bonders, De-Bonders & Aligners
A range of permanent and non-permanent wafer bonders for MEMS, advanced packaging, 2.5 & 3d integration, power devices and led applications, plus debonders for thin wafer applications. From manual system for R&D and pilot production, through semi to fully automatic models. Capabilities include low-high force bonding, anodic bonding, thermo-compression bonding, eutectic bonding, glass frit bonding, fusion & adhesive bonding etc.

SÜSS ReMan
Remanufactured Equipment
Certified refurbishment of SÜSS MicoTec equipment using manufacturer-specified original parts, restored to its original condition or even adding features to enhance performance e.g. software and optics. Systems are prepared according the original specifications and performance data, incorporate six months warranty, safety feature updates and pre and final acceptance tests etc. Remanufactured systems are also available for purchase.

ATV

Semiconductor Furnaces

For research or production, the PEO range of Quartz Tube Furnaces features fast ramping and cooling in a space saving & energy efficient design. They can reach temperatures ranging to 1100°C and devices up to 300mm diameter. Applications include: Oxidation, Annealing, LPCVD, Diffusion, Polyimide Curing, Thickfilm Firing etc.

PACTECH

UBM, Solder Ball Attach & Reflow Equipment

PacTech provides state-of-the-art automated equipment to the Wafer Level Packaging and Backend Industries. This equipment is divided into three separate platforms: e-Ni/Au Plating, Solder Bumping, and Backend Assembly.

PLASMA ETCH INC.

Reactive Ion Etching & Plasma Ashing Systems

Bench-top & industrial sized systems for etching wafers or PCB's. Electrode configurations and 13.56MHz power sources for ashing, isotropic or anisotropic processing.

SEMIPROBE

Manual Probe Stations

LAB assistant: low cost compact manual probing system with stage, chuck, optics & manipulators for die and up to 300mm in diameter, including partial and broken wafers. Manual PS4L: modular probe system up to 450mm with upgrade path to fully auto capability.

SEMIPROBE

Semi & Fully automatic Wafer Probers

Based on SemiProbe's modular Probe System For Life (PS4L) platform, the product range includes semiautomatic probers for up to 100, 150, 200 & 300mm wafers and fully automatic versions through to 450mm. Their robust design and open software architecture enables future upgrades for larger wafer sizes, automation and functionality. Test capabilities include: High Voltage, MEMS, Vacuum, Magnetic Stimulation etc.

ADT

Wafer Mounting Equipment

Up to 300mm manual & 200mm semi-automatic mounting systems for standard & UV tapes. Manual systems feature custom designs for non-standard frames. Semi-auto systems produce bubble free tape application on standard, thin & fragile wafers.

ADT

Manual & Semiautomatic & Fully Automatic Wafer Saws

With high accuracy cutting, high and lower power, single or dual spindle and large area options, ADT offers the most comprehensive range of manual and semi-automatic dicing systems for 50 to 300mm wafers or devices. Capabilities include Multi-panel processing, easy-to-use software, broken or partial wafer alignment etc.

ADT

Wafer Cleaning & Peripheral Dicing Equipment

The 977 Wafer Cleaner from ADT is a free standing system for cleaning workpieces after dicing. The system features a robust design and smart user interface & is offered in three versions: WCS-977 up to 8" dia, WCS-977LA up to 12" dia & WCS-977D standalone coating -de-coating system. In addition, ADT offer a wide range of peripheral equipment including filtration systems, CO_2 inline injectors, UV tape curing systems, chillers, mist venting etc.

ATV

Diamond Scribers

Precision diamond scribers for manual scribing of ceramic/glass substrates and silicon wafers. Vacuum chuck, fine adjust, cross hair alignment.

AMADYNE

Automatic Batch Assembly Equipment

The CAT is an automatic batch system capable of die and component assembly in a small footprint. The CAT is designed for R&D through low-medium volume microelectronic assembly operations and offers exceptional flexibility, using some of the latest positioning, image processing, electronics and software technology available.

AMADYNE

Flexible Automatic Die Bonders

Fully automatic, inline capable, flexible die assembly system for microsystem assembly operations including pick & place, eutectic or epoxy die bonding, sort or flip chip applications and component test integration.

ATV

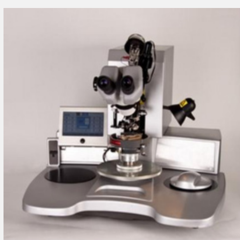
Vacuum Soldering Equipment & Sealing

Benchtop to inline vacuum solder reflow ovens with rapid thermal annealing & high temperature capability, for void-free solder reflow, brazing and sealing. Capabilities include: formic or H2 processing, high-vacuum getter activation & thermo-compression bonding. Reflow profiles are created simply using ATV's WIN-ATV software, which allows the user to program up to 100 process steps to create the ideal reflow profile.

ATV

Sintering Press

The PHP is designed for LTCC and other sintering applications where the control of temperature & pressure are process critical. The system is a maintenance free, pneumatically driven, sinter press for up to 50kN, min. 500N, ± 1% at 20kN pressures. The press incorporates ATV's proven furnace technology for processing sintered components up to 1000°C.



MPP – Micro Point Pro

Manual Wire Bonders

Formerly Kulicke & Soffa (K&S). Manual to semi-automatic models for gold ball & bump bonding and wedge bonding. Convertible thermosonic ball & wedge bonders. Versions with either analogue or touch screen controls.

KULICKE & SOFFA - ORTHODYNE

Automatic Ball Bonders & Bumpers

K&S high-speed gold ball bond systems for IC, MCM & large area hybrid assembly. Manual load pedestals to automatic handling systems. Ultra-high-speed ball bumping systems for up to 12” wafers.

KULICKE & SOFFA - ORTHODYNE

Automatic Wedge Bonders

High speed, high-quality, rotary head wedge bonders with large bonding areas, for inline or stand-alone use. Bond process monitoring, advanced vision alignment system, graphical bond head setup system. For:

- Fine wire Al/Au
- Large wire: Al, Cu, Al-Cu & PowerRibbon

KULICKE & SOFFA - ORTHODYNE

Leadframe Bonder for Power Devices

Three models of PowerFusion bonders are available. The TL Model is the perfect choice for bonding TO power devices while the HL Model provides the accuracy and capability required to process the most advanced power packages. The HLx Model can handle extra-wide matrix and IPM leadframes up to 105 mm wide.

NORDSON-DAGE

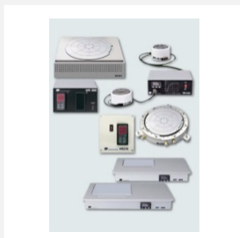
Bond Test Equipment

Manual and automated wire pull, bond & die shear, bump test, tweezer pull and stud pull etc. Bond testing with single or multi-function cartridges, SQL databases & reporting software, wafer handling solutions, inspection and alignment cameras. Up to 200Kg shear, 100Kg pull and push tests up to 50Kg etc.

NORDSON-DAGE

Micro-Materials Test Equipment

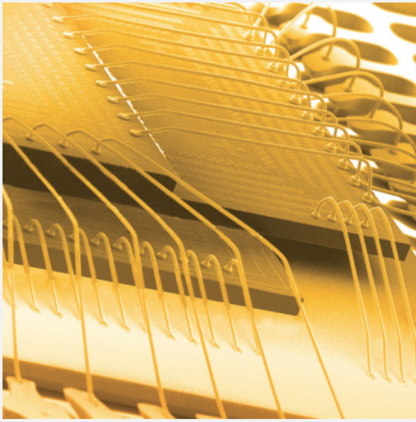
The 4000Plus micro materials tester is fully optimised for small scale testing providing integrated imaging systems, precise positioning technology and micro gripping techniques. Applications include: Tension, Compression, Flexural, Fatigue, Brittle fracture, Peel, Torsion, Creep, plus all standard bond test methods: pull & shear etc.



INSETO

Hot Plates

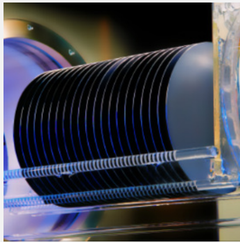
High precision hot plates & chucks. Excellent uniformity, max temp 360°C/450°C higher on request. Solid, uniform, robust & reliable customised versions available on request.



CONSUMABLE DIVISION:

Inseto's Consumable Division provides production materials, services and machine consumable tools utilised in the manufacturing and research of semiconductor, microelectronic and related devices. These products are supplied throughout the UK, Ireland, Sweden, Denmark, Norway and Finland.

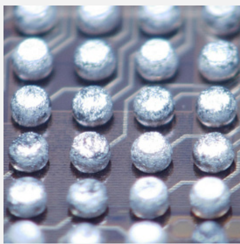
Products & services include: semiconductor & silica wafers, sub-contract wafer bumping grinding & dicing, bonding wires & ribbons, plated wire & ribbons, precision stampings, solder spheres & preforms , hermetic glass & ceramic packages, thick film materials, metalised thin film substrates, thermal dissipation materials, welding electrodes & thermodes, plus bonding wedges, capillaries, die collets & dicing blades etc.



INSETO

Semiconductor Wafers, Substrates and Coatings

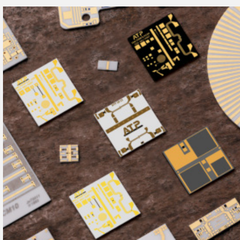
A wide range of high-quality virgin or coated silicon wafers from 1 to 12" (25-300mm), in every orientation, resistivity and thickness available for rapid delivery from our large inventory. High purity fused silica and glass wafers-substrates from 50-200mm (2-8”). Oxidised and nitride wafer coatings, grid patterns and wafer dicing also ex-stock or on a rapid turnaround.



PACTECH

Sub-contract Wafer Bumping, Grinding & Dicing

PacTech offers a complete set of wafer level and backend services, including: sawing, dicing, redistribution, re-passivation, backside laser marking, backside coating, test die, and assembly. In addition, PacTech owns the latest metrology and analytical equipment to help in the development and production processes, including: x-ray, shear test, AOI, ICP, AA, probing, high speed ball pull, chemical analysis, etc.



ATP

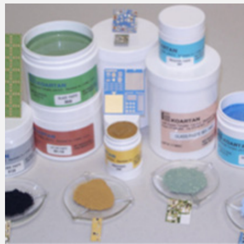
Metalised Thin Film Circuits

High-quality custom "Thin-Film Circuits" manufactured with a quick turn-around according to customers specific requirements. Available in a wide selection of materials including Al_20_3, AIN, BeO, Fused Silica/Quartz, Sapphire and Hi-K Dielectrics with bondable and solderable metallisations etc.

MICROCERTEC

Precision and Machined Ceramics

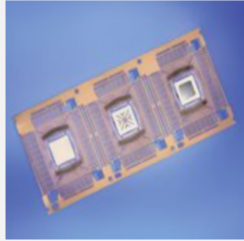
High Precision Grinding, Machining & Micro-machining of Alumina, Zirconium Oxide, Aluminium Nitride, Sapphire, Silicon, Piezoelectric, Silicon Carbide & Silicon Nitride Ceramics.



KOARTAN

Thick Film Materials

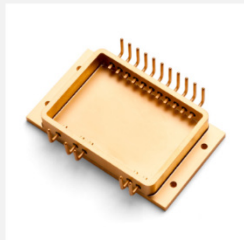
Environmentally friendly thick film pastes for the microelectronic industry include silver, gold, and copper conductors, resistors, NTC and PTC thermistors, multilayer, cross-over, and capacitor dielectrics, sealing glasses, aluminium-nitride compatible pastes, thin-print, etch-able, and nickel plate-able conductors.



DELO

Die Attach Adhesives

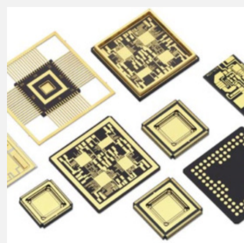
Fast curing epoxy adhesives. Optional light-fixing capability. High temperature resistance, up to 250°C. Suitable for various substrates including leadframes, FR4 & ceramic. Conductive & non-conductive materials.



EGIDE

Ceramic & Glass Sealed packages

Hermetic packages including butterfly, bath-tub, platform, high power, feed-throughs, transistor outline TO-header for low/high power devices, miniature hermetic feed-throughs, multi-pin microcircuit packages, & precision machined Kovar housings.



EGIDE-SANTIER

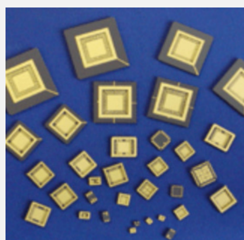
Co-Fired Ceramics

HTCC packages. Multi-layer MCM's, PGA's. High I/O interconnects. Matched metal systems. Power, RF & FO applications.

EGIDE-SANTIER

Thermal Management Materials

Copper tungsten (5 grades). Copper molybdenum. Cu-MoCu-Cu laminate. SilvarTM. VHTC diamond composites.



SPECTRUM SEMICONDUCTOR MATERIALS

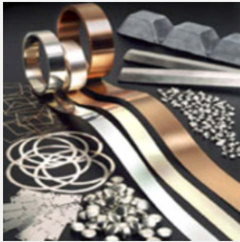
Ex-stock Ceramic & Glass Sealed Hermetic Packages

Off-the shelf TO-3, TO-5, TO-18, TO-46, TO-25X, LCC's, ceramic PGA's, cerdip's, SOP's, side-braze, and metal hybrid packages.

COINING

Bonding & Micro-Welding Wires & Ribbons

High quality bonding wires and ribbons, including Gold - 12.5µm upwards, Aluminium - Up to 500µm, 1% Silicon Aluminium (Al/Si), 0.5% Mg Aluminium, Copper and Silver. Plated Silver and Copper wires and ribbons for Welding.

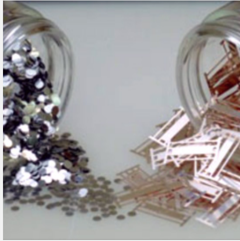


COINING
Solder Preforms, Ribbons & Spheres

Eutectic gold alloys.

All indium, tin / lead & other alloys.

Wide range of open tools or EDM for special profiles & shapes.

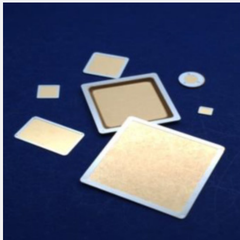


COINING
Precision Metal Stampings

Base materials of copper, kovar, molybdenum etc.

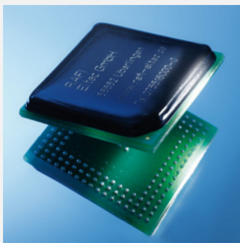
Clad with solder, or aluminium, stamped to requirement.

Extensive open tool list. Packaged in: waffle packs, tape & reel or vials.



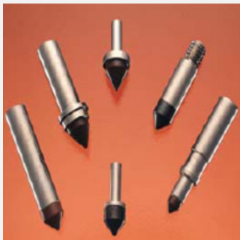
COINING
Package Lids

Cover assemblies in Kovar or alloy 42 standard base materials, aluminium, titanium and stainless steel also available. Plated with gold over nickel, to provide s highly solderable surface. AuSn solder preform tack welded.



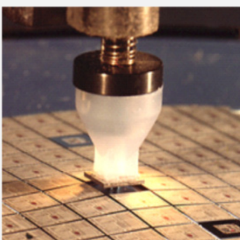
DELO
Encapsulation Materials

Glob-tops for small area encapsulation; Dam & Fill for large area (>2mm^2) encapsulation. Very high chemical and temperature resistance. High Tg, low CTE materials. Suitable for CTE-matching applications. Easy to dispense, meet JEDEC MSL Level 1 requirements. Cured adhesive can be laser marked, electro-plated, routed and diced.



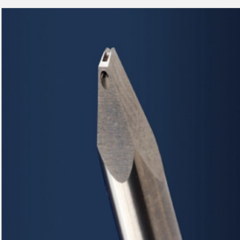
CRAFTRONICS
Assembly Consumables

Die pick-up tips - rubber, plastic, high temp, eject needles, stamping tools, dispensing nozzles, Royce wire pull hooks & shear tools, EFO's, and heater plates and window clamps etc.



MICRO POINT PRO
Die Bonding Tools & Collets

A comprehensive range of tools materials including: Delrin, Tungsten Carbide, Vespel & Ceramic, for Eutectic, Flipchip & Adhesive Bonding. Eject Needles, Dispensing Heads & Tooling, compatible with all die attach and die sort systems.



KULICKE & SOFFA – K&S
Bonding Wedges & Ribbon Bonding Tools

An extensive selection of standard & deep access wedges for Au, Al, Cu & Pd wire and ribbon bonding. Compatible with all manual & automatic wedge bonders. Formerly the K&S MicroSwiss Bonding Tools division.

KULICKE & SOFFA – K&S

Ball Bond & Bump Bonding Capillaries

Market leading capillaries for all gold and copper ball & bump bonding on either manual or fully automatic bonders. BPP - bond pad pitch capability down to 25 microns.

AIT

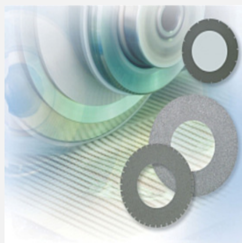
OEM & Custom Parallel Gap Welding Electrodes

AIT's micro resistance welding electrodes come in either square shank or round shank designs, which are built to match the electrode holder design. OEM equivalents and custom versions include: Offset Electrodes, Probe Electrodes, Straight Electrodes, Eccentric Electrodes, 1/4 inch Tip Electrodes etc. for all makes and models of equipment.

AIT

OEM & Custom Hot Bar Soldering Thermodes

AIT's Pulsed Heat Soldering tools for reflow, ACF bonding and staking are available in OEM equivalents and custom versions including: High Thermal Mass Thermodes, Shank Mounted Thermodes, Flat Blade Thermodes and Folded Thermodes etc.



ADT

Hubless Dicing Blades

Resin bonded dicing blades for hard & brittle materials. Metal sintered blades for medium to hard materials. Nickel bonded blades for soft materials.

ADT

Precision Dicing Flanges & Dressing Boards

Available for all blade types in the range of 2"- 5", ADT's extensive line of flanges exhibit high accuracy, excellent performance, ease of use and affordability etc. ADT offers a wide range of Dressing Boards for different applications. You can choose from different abrasives, mesh sizes and dimensions to fit your needs.

KULICKE & SOFFA – K&S

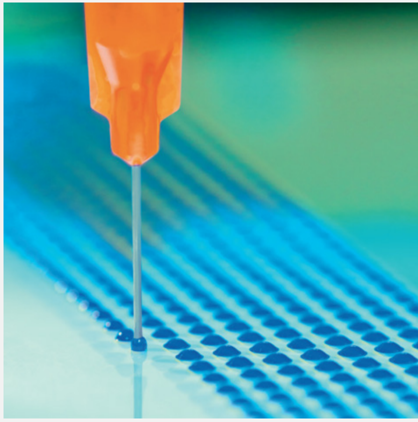
Hub Dicing Blades

Hub blades for advanced semiconductor & package dicing, known formerly as Semitec. For silicon, copper & low-k metallised wafers. Bevel-series blades for LED dicing. New uni-plus series for package dicing..

ADT

Wafer Frames & Cassettes

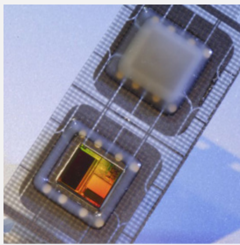
Frame sizes accommodate wafers & substrates from 3" up to 12" manufactured from hardened magnetic stainless steel with an electro-polish surface finish.



ADHESIVE DIVISION:

Inseto's Adhesive Division provides technically advanced adhesives for bonding, sealing & encapsulation applications to customers throughout the UK & Ireland. Exclusively representing DELO Industrial Adhesives, our specialists have the technical expertise to advise on all your project requirements.

DELO manufactures a comprehensive range of UV cured or light activated Epoxies, light cured Acrylates, light / heat cured Epoxies, light / anaerobic curing adhesives, 2 part Polyurethanes, 1 & 2 part Epoxies, Cyanoacrylates and single part Silicones. Inseto can also offer tailor-made adhesive solutions that meet your technical bonding requirements. DELO's product range comprises:



DELO-KATIOBOND

Light Activated Epoxies

UV / VIS-curing epoxy adhesives. Visible-light activated epoxies for bonding opaque components. Single-part solvent-free adhesives for bonding, sealing and potting applications. Fast-curing for short cycle times and increased throughput. High thermal and chemical resistance.

DELO-PHOTOBOND

Light Cured Acrylates

UV / VIS-curing acrylate adhesives for applications with one transparent component. Single-part solvent-free adhesives, used for rapid bonding, sealing & joining of plastics, metals and glass. Highly flexible adhesives suitable for stress-equalising applications.

DELO-DUALBOND

Light and/or Heat-Curing Epoxies & Acrylates

Combination cure of heat and / or UV light. Independent curing mechanisms. Ideal for high-accuracy applications, also for curing in shadow zones.

DELO-DUALBOND

Light and Moisture-Cured Acrylates

Dual-curing system for panel and touchscreen applications. Fast curing with UV light, subsequent moisture curing in shadow zones.

DELO-DUALBOND

Light & Anaerobic-Curing Adhesives

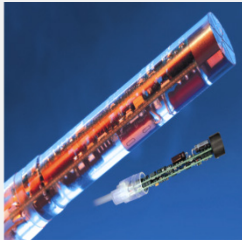
Cure anaerobically in the presence of metal ions. UV light used to cure the edge of the joint. Especially for high thermal and chemical resistance.

Image Courtesy & Copyright: ebm-Pabst GmbH & Co. KG

DELOMONOPOX

One Part Epoxies

Single-part heat-cured epoxies. Curing temperatures as low as 60°C. Very high thermal resistance up to 250°C. Used as adhesives and casting resins in electronic, electrical and mechanical engineering applications.



DELO-DUOPOX

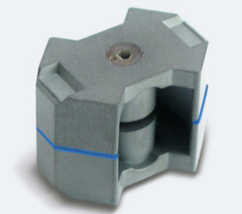
Two Part Epoxies

High strength, two-part, cold cured epoxy resin adhesives for bonding, casting and sealing of joints where curing with heat is not an option. Excellent adhesion to a wide range of materials.

DELO-PUR

Polyurethanes

Two-part cold curing adhesive for bonding, casting & sealing of joints. Available in AUTOMIX cartridges for use in high strength applications where flexibility is required or for filling of large gaps.



DELO-ML

Anaerobic Adhesives

Single-part solvent-free adhesives for bonding in the presence of metal and the absence of air. High, medium and low bond strength options. For magnet and ferrite bonding. Very high thermal and chemical resistance.

DELO-CA

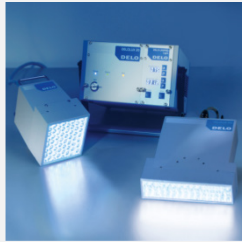
Instant Adhesives

Cyanoacrylate adhesives, moisture curing for general bonding applications. More commonly known as super glue or instant adhesives they provide an initial bond strength in seconds.

DELO-GUM

Silicone Adhesives

Moisture cured silicone adhesives. Excellent resistance to temperature, weathering, ageing & with a high elongation at tear. For fixing, sealing, potting and for where large gaps need to be filled.



DELOLUX 20

Large Area Curing Equipment

Large-area LED lamp for bigger illumination area. Available in 365nm, 400nm and 460nm options. Use in standalone mode, or in-line production. Even cure over the whole area. Long life time of 10K on-hours minimum.

DELOLUX 50

Spot Curing Equipment

Pin-point LED lamp for spot curing with very high intensity (up to 12,000 mW/cm^2). Maximum of 4 LED heads can be connected. Lens diameter from 3mm to 15mm. Available in 365nm and 400nm options. Long life time of 10K on-hours.

DELOLUX 80

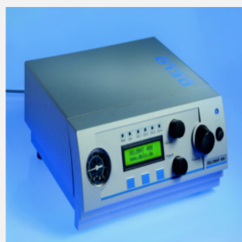
High Intensity Curing Equipment

Closed circuit, liquid-cooled high intensity LED lamp. Available in 365nm, 400nm & 460nm options. Focused beam up to a distance of 25mm. Long life time of 10K on-hours minimum.

DELOLUXCONTROL

Light Intensity Measurement Equipment

Process control light-intensity meter. Suitable for use with LED lamps and halogen-bulb lamps. Large display for easy reading. Battery operated. Very high resolution of 0.1 mW/cm^2.



DELOMAT

Dispensing Equipment

For semi to fully automatic dispensing, with up to 4 independently controlled work stations. Universal dispensing from pressure tank, cartridge & syringe. For low viscosity to pasty adhesives.

DELO-DOT-PN2

Micro Dispensing Equipment

Pneumatic dispensing valve. Combines precision, speed and slim dimensions. Cutting-edge actuator. Modular design for ease of cleaning. Easily integrated into existing production lines.

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